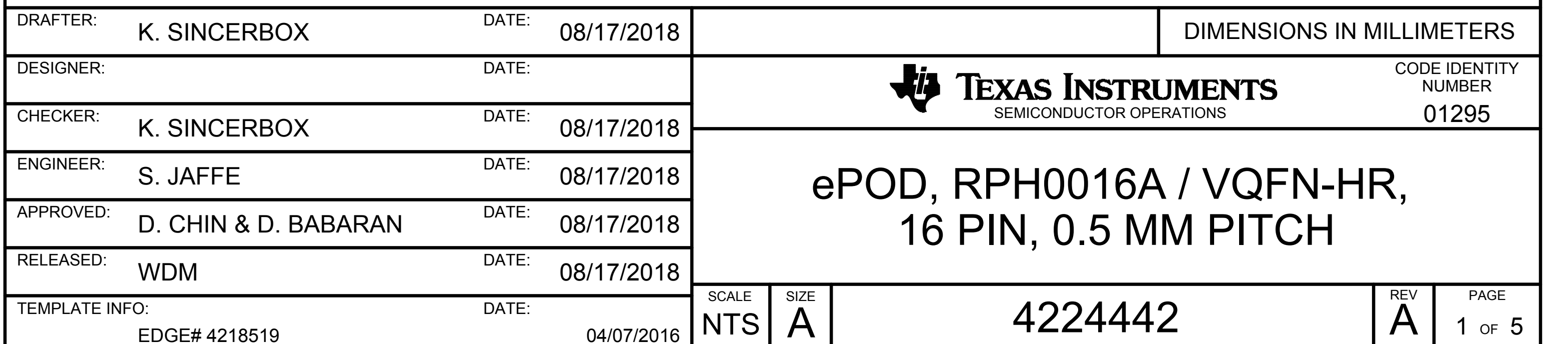
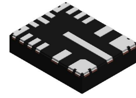
DATA BOOK
PACKAGE OUTLINE





PACKAGE OUTLINE

VQFN-HR - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

B 3.6 3.4 A

PIN 1 INDEX AREA

4.6 4.4

0.1 MIN

(0.05)

SECTION A-A
TYPICAL

1.0 0.8

C

SEATING PLANE

0.05 0.00

0.08 C

0.000 PKG ℄

0.5 0.5

2X 1.0 0.8

4X (0.3)

(0.15) TYP

(0.2) TYP

2X 0.525 0.325

7X 0.725 0.525

6 10

2X 2

2X 1.525

2X 1.025

2X 0.525

2X 0.25 0.15

0.1Ⓜ C A B
0.05Ⓜ C

A A

9X 0.3 0.2

0.1Ⓜ C A B
0.05Ⓜ C

0.000 PKG ℄

2.825 2.625

2X 0.55

4X (0.325)

2X 0.45 0.35

0.1Ⓜ C A B
0.05Ⓜ C

2X 1.5

2X 1.95

1 15

PIN 1 ID

16

4X 0.35 0.25

0.1Ⓜ C A B
0.05Ⓜ C

0.4 0.3

0.1Ⓜ C A B
0.05Ⓜ C

SYMM ℄

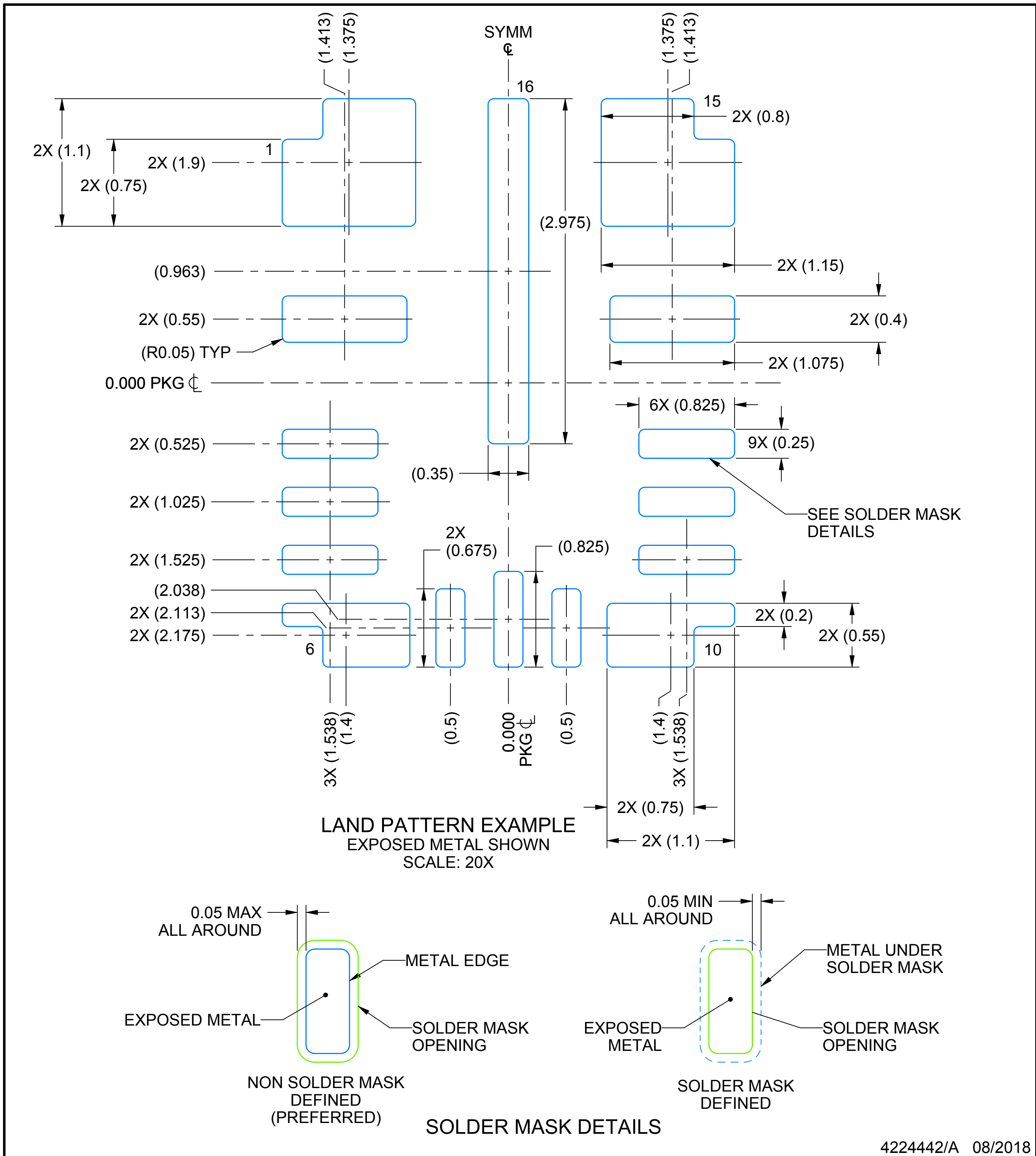
2X 0.925 0.725

2X 1.05 0.85

4224442/A 08/2018

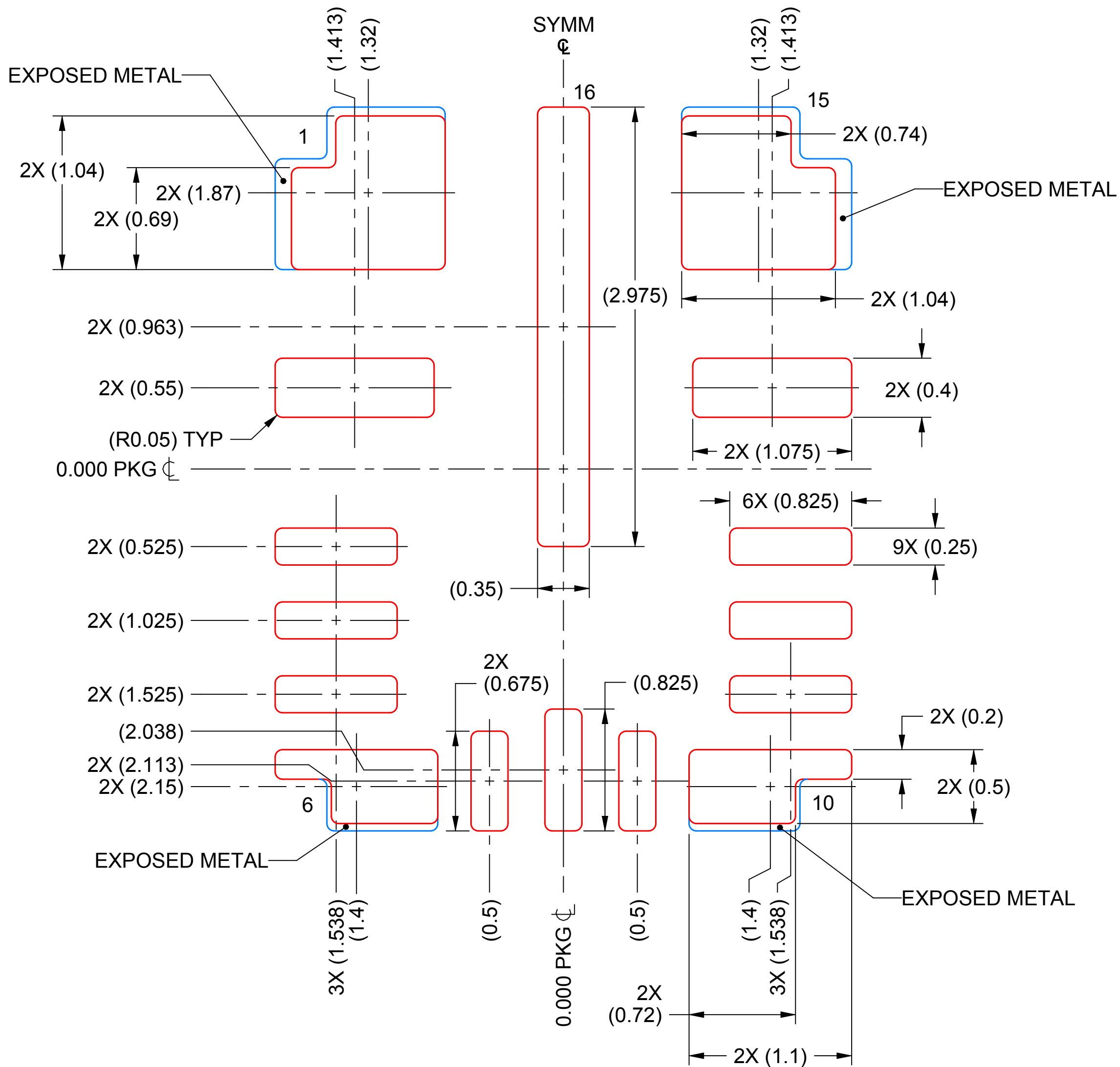
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 20X

PADS 1 & 15:
85% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
PADS 6 & 10:
90% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2175530	08/17/2018	S. JAFFE / K. SINCERBOX